

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L9	8311	(438/710-712,714,716,787-788,791-792,905-906).CCLS.	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2008/06/21 20:42
L10	7484	L9 and @ad<"20041202"	US-PGPUB; USPAT; EPO; JPO	ADJ	ON	2008/06/21 20:42
L11	16	L10 and cleaning and (chuck with cover)	US-PGPUB; USPAT; EPO; JPO	ADJ	ON	2008/06/21 20:42
L12	13	11 and @ad<"20030116"	US-PGPUB; USPAT; EPO; JPO	ADJ	ON	2008/06/21 20:43
L13	3	12 and (clamp\$3 with (cover or dummy wafer))	US-PGPUB; USPAT; EPO; JPO	ADJ	ON	2008/06/21 21:45
L14	15	10 and (clamp\$3 with (cover or dummy wafer))	US-PGPUB; USPAT; EPO; JPO	ADJ	ON	2008/06/21 21:47
L15	14	14 and @ad<"20030116"	US-PGPUB; USPAT; EPO; JPO	ADJ	ON	2008/06/21 21:47
L16	143	(plasma with CVD) and (clamp\$3 with (cover or dummy wafer))	US-PGPUB; USPAT; EPO; JPO	ADJ	ON	2008/06/21 21:52
L17	95	16 and @ad<"20030116"	US-PGPUB; USPAT; EPO; JPO	ADJ	ON	2008/06/21 21:52
L18	49	17 and cleaning	US-PGPUB; USPAT; EPO; JPO	ADJ	ON	2008/06/21 21:53

L19	5	18 and (clamp\$3 with (cover or dummy wafer) with (chuck or substrate support))	US-PGPUB; USPAT; EPO; JPO	ADJ	ON	2008/06/21 21:54
L20	12	17 and (clamp\$3 with (cover or dummy wafer) with (chuck or substrate support))	US-PGPUB; USPAT; EPO; JPO	ADJ	ON	2008/06/21 21:56
L21	7	20 not 19	US-PGPUB; USPAT; EPO; JPO	ADJ	ON	2008/06/21 21:57
L22	1182	(plasma) and (clamp\$3 with (cover or dummy wafer))	US-PGPUB; USPAT; EPO; JPO	ADJ	ON	2008/06/21 22:41
L23	618	22 and @ad<"20030116"	US-PGPUB; USPAT; EPO; JPO	ADJ	ON	2008/06/21 22:41
L24	190	23 and cleaning	US-PGPUB; USPAT; EPO; JPO	ADJ	ON	2008/06/21 22:41
L25	15	24 and (clamp\$3 with (cover or dummy wafer) with (chuck or substrate support))	US-PGPUB; USPAT; EPO; JPO	ADJ	ON	2008/06/21 22:42
L26	10	25 not 20	US-PGPUB; USPAT; EPO; JPO	ADJ	ON	2008/06/21 22:42
L27	39	23 and (clamp\$3 with (cover or dummy wafer) with (chuck or substrate support))	US-PGPUB; USPAT; EPO; JPO	ADJ	ON	2008/06/21 22:47
L28	24	27 not 25	US-PGPUB; USPAT; EPO; JPO	ADJ	ON	2008/06/21 22:47
L29	3	(plasma with CVD) and (clamp\$3 with (cover wafer))	US-PGPUB; USPAT; EPO; JPO	ADJ	ON	2008/06/21 22:54

6/21/2008 11:11:10 PM

C:\Documents and Settings\bau\My Documents\EAST\Workspaces\Plasma Processing
 \10657207 cleaning of reaction chamber using a cover on the chuck or support electrode.
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